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**Universal serial bus interfaces for data and power –
Part 1-3: Universal Serial Bus interfaces – Common components –
USB Type-C™ cable and connector specification**

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UNIVERSAL SERIAL BUS INTERFACES FOR DATA AND POWER –

Part 1-3: Universal Serial Bus interfaces – Common components – USB Type-C™ cable and connector specification

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The text of this standard is based on the following documents:

CDV	Report on voting
100/2587/CDV	100/2681/RVC

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

A list of all parts in the IEC 62680 series, published under the general title *Universal serial bus interfaces for data and power*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

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This standard is the USB-IF publication USB Type-C™ Cable and Connector Specification Revision 1.1.

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Universal Serial Bus Type-C Cable and Connector Specification

**Revision 1.1
April 3, 2015**

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Specification Work Group Chairs / Specification Editors

Intel Corporation
(USB 3.0 Promoter
company)

Seagate

Yun Ling – Mechanical WG co-chair, Mechanical Chapter Co-editor
Bob Dunstan – Functional WG co-chair, Specification Co-author
Brad Saunders – Plenary/Functional WG chair, Specification Co-author

Alvin Cox, Mechanical WG co-chair, Mechanical Chapter Co-editor

Specification Work Group Contributors

Advanced-Connectek, Inc.
(ACON)

Advanced Micro Devices

Agilent Technologies, Inc.

Apple

Cypress Semiconductor

Dell

DisplayLink (UK) Ltd.

Electronics Testing Center,
Taiwan

Foxconn

Foxlink/Cheng Uei Precision
Industry Co., Ltd.

Google

Granite River Labs

Hewlett Packard
(USB 3.0 Promoter company)

Glen Chandler

Jeff Chien

Lee (Dick Lee) Ching

Conrad Choy

Steve Capezza

James Choate

Mahmoud Amini

Sree Anantharaman

Paul Baker

Jason Chung

David Conroy

Bill Cornelius

Mark Fu

Rushil Kadakia

Mohammed Hijazi

David Meyers

Pete Burgers

Sophia Liu

Asroc Chen

Allen Cheng

Jason Chou

Edmond Choy

Bob Hall

Robert Chen

Sunny Chou

Carrie Chuang

Wen-Chuan Hsu

Alex Hsue

Joshua Boilard

Jim Guerin

Jeffrey Hayashida

Mark Hayter

Mike Engbretson

Alan Berkema

Robin Castell

Vicky Chuang

Aven Kao

Danny Liao

Alan MacDougall

Walter Fry

William Ferry

Zheng Gao

Girault Jones

Keong Kam

Min Kim

Chris Ligtenberg

Anup Nayak

Jagadeesan Raj

Sean O'Neal

Ernesto Ramirez

Richard Petrie

Chien-Ping Kao

Ji Li

Ann Liu

Terry Little

Steve Sedio

Armando Lee

Dennis Lee

Justin Lin

Tse Wu Ting

Nithya Jagannathan

Lawrence Lam

Ingrid Lin

Adam Rodriguez

Johnson Tan

Michael Krause

Jim Mann

Alan Tsai

Stephen Yang

Will Harris

Nathan Ng

James Orr

Keith Porthouse

Sascha Tietz

Colin Whitby-Stevens

Dennis Yarak

Sanjay Sancheti

Subu Sankaran

Thomas Voor

Pei Tsao

AJ Yang

Yuan Zhang

Jessica Zheng

Andy Yao

Steve Tsai

Wen Yang

Wiley Yang

Junjie Yu

David Schneider

Ken Wu

Linden McClure

Mike Pescetto

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Hirose Electric Co., Ltd.	Jeremy Buan William MacKillop	Gourgen Oganessyan	Sid Tono
Intel Corporation (USB 3.0 Promoter company)	Dave Ackelson Mike Bell Kuan-Yu Chen Hengju Cheng Bob Dunstan Paul Durley Howard Heck Hao-Han Hsu Abdul (Rahman) Ismail	James Jaussi Luke Johnson Jerzy Kolinski Christine Krause Yun Ling Xiang Li Guobin Liu Steve McGowan	Chee Lim Nge Sridharan Ranganathan Brad Saunders Amit Srivastava Ron Swartz Karthi Vadivelu Rafal Wielicki
Japan Aviation Electronics Industry Ltd. (JAE)	Kenji Hagiwara Masaki Kimura Toshio Masumoto Joe Motojima Ron Muir Tadashi Okubo Kazuhiro Saito	Kimiaki Saito Yuichi Saito Mark Saubert Toshio Shimoyama Tatsuya Shioda Atsuo Tago Masaaki Takaku	Jussi Takaneva Tomohiko Tamada Kentaro Toda Kouhei Ueda Takakazu Usami Masahide Watanabe Youhei Yokoyama
JPC/Main Super Inc.	Sam Tseng	Ray Yang	
LeCroy Corporation	Daniel H. Jacobs		
Lenovo	Rob Bowser Tomoki Harada	Wei Lie	Howard Locker
Lotes Co., Ltd.	Ariel Delos Reyes Ernest Han Mark Ho	Regina Liu-Hwang Max Lo Charles Kaun	JinYi Tu Jason Yang
LSI Corporation	Dave Thompson		
Luxshare-ICT	Josue Castillo Daniel Chen Lisen Chen	CY Hsu Alan Kinningham John Lin	Stone Lin Pat Young
MegaChips Corporation	Alan Kobayashi		
Microchip (SMSC)	Josh Averyt Mark Bohm	Donald Perkins	Mohammed Rahman
Microsoft Corporation (USB 3.0 Promoter company)	Randy Aull Fred Bhesania Anthony Chen Marty Evans Vivek Gupta Robbie Harris	Robert Hollyer Kai Inha Jayson Kastens Andrea Keating Eric Lee	Ivan McCracken Toby Nixon Gene Obie Srivatsan Ravindran David Voth
MQP Electronics Ltd.	Sten Carlsen	Pat Crowe	
Nokia Corporation	Daniel Gratiot Pekka Leinonen	Samuli Makinen Pekka Talmola	Timo Toivola Panu Ylihaavisto
NXP Semiconductors	Vijendra Kuroodi	Guru Prasad	
Renesas Electronics Corp. (USB 3.0 Promoter company)	Nobuo Furuya	Philip Leung	Kiichi Muto

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Rohm Co., Ltd.	Mark Aaldering	Arun Kumar	Takashi Sato
	Kris Bahar	Chris Lin	Hiroshi Yoshimura
	Yusuke Kondo		
Samsung Electronics Co., Ltd.	Soondo Kim	Jagoun Koo	Jun Bum Lee
	Woonki Kim	Cheolho Lee	
Seagate	Alvin Cox	Tom Skaar	Dan Smith
	Tony Priborsky		
STMicroelectronics (USB 3.0 Promoter company)	Nicolas Florenchie	Christophe Lorin	Federico Musarra
	Joel Huloux	Patrizia Milazzo	Pascal Legrand
Tektronics, Inc.	Randy White		
Texas Instruments (USB 3.0 Promoter company)	Jawaid Ahmad	Win Maung	Anwar Sadat
	Richard Hubbard	Lauren Moore	Sue Vining
	Scott Jackson	Martin Patoka	Deric Waters
	Yoon Lee	Brian Quach	
	Grant Ley	Wes Ray	
Tyco Electronics Corp. (TE Connectivity Ltd.)	Max Chao	Jim McGrath	Scott Shuey
	Robert E. Cid	Takeshi Nakashima	Hidenori Taguchi
	Kengo Ijiro	Luis A. Navarro	Bernard Vetten
	Eiji Ikematsu	Masako Saito	Ryan Yu
	Joan Leu	Yoshiaki Sakuma	Sjoerd Zwartkruis
	Clark Li	Gavin Shih	
	Mike Lockyer	Hiroshi Shirai	
VIA Technologies Inc.	Terrance Shih	Jay Tseng	Fong-Jim Wang

Pre-Release Draft Industry Reviewing Companies That Provided Feedback

Aces	Johnson Components & Equipment Co., Ltd.	Parade Technology
Allion Labs, Inc.	Joinsoon Electronics Mfg. Co. Ltd.	Pericom
Analogix Semiconductor	JST Mfg. Co., Ltd.	Qualcomm
BizLink International Corp.	Korea Electric Terminal	Semtech Corporation
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Fujitsu Ltd.	NXP Semiconductors	Sony Corporation
Industrial Technology Research Institute (ITRI)	PalCONN/PalNova (Palpilot International Corp.)	Sumitomo Electric Industries
		Toshiba Corporation

Revision History

Revision	Date	Description
1.0	August 11, 2014	Initial Release
1.1	April 3, 2015	Reprint release including incorporation of all approved ECNs as of the revision date plus editorial clean-up.

1 Introduction

With the continued success of the USB interface, there exists a need to adapt USB technology to serve newer computing platforms and devices as they trend toward smaller, thinner and lighter form-factors. Many of these newer platforms and devices are reaching a point where existing USB receptacles and plugs are inhibiting innovation, especially given the relatively large size and internal volume constraints of the Standard-A and Standard-B versions of USB connectors. Additionally, as platform usage models have evolved, usability and robustness requirements have advanced and the existing set of USB connectors were not originally designed for some of these newer requirements. This specification is to establish a new USB connector ecosystem that addresses the evolving needs of platforms and devices while retaining all of the functional benefits of USB that form the basis for this most popular of computing device interconnects.

1.1 Purpose

This specification defines the USB Type-C™ receptacles, plug and cables.

The USB Type-C Cable and Connector Specification is guided by the following principles:

- Enable new and exciting host and device form-factors where size, industrial design and style are important parameters
- Work seamlessly with existing USB host and device silicon solutions
- Enhance ease of use for connecting USB devices with a focus on minimizing user confusion for plug and cable orientation

The USB Type-C Cable and Connector Specification defines a new receptacle, plug, cable and detection mechanisms that are compatible with existing USB interface electrical and functional specifications. This specification covers the following aspects that are needed to produce and use this new USB cable/connector solution in newer platforms and devices, and that interoperate with existing platforms and devices:

- USB Type-C receptacles, including electro-mechanical definition and performance requirements
- USB Type-C plugs and cable assemblies, including electro-mechanical definition and performance requirements
- USB Type-C to legacy cable assemblies and adapters
- USB Type-C-based device detection and interface configuration, including support for legacy connections
- USB Power Delivery optimized for the USB Type-C connector

The USB Type-C Cable and Connector Specification defines a standardized mechanism that supports Alternate Modes, such as repurposing the connector for docking-specific applications.

1.2 Scope

This specification is intended as a supplement to the existing [USB 2.0](#), [USB 3.1](#) and [USB Power Delivery](#) specifications. It addresses only the elements required to implement and support the USB Type-C receptacles, plugs and cables.

Normative information is provided to allow interoperability of components designed to this specification. Informative information, when provided, may illustrate possible design implementations.